

NOT RECOMMENDED FOR NEW DESIGN USE DGD21814M



DGD21814

HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-14 (Type TH)

Description

The DGD21814 is a high-voltage/high-speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half-bridge configuration. High-voltage processing techniques enable the DGD21814's high-side to switch to 600V in a bootstrap operation.

The DGD21814 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD21814 is offered in SO-14 package and the operating temperature extends from -40°C to +125°C.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

V_{CC} V_{CC} HIN V_{SS} COM LO Typical Configuration

Features

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 1.9A Source / 2.3A Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Wide Low-side Gate Driver and Logic Supply: 10V to 20V
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for High and Low Side Drivers
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.
- https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: SO-14 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.142 grams (Approximate)



Top View

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD21814S14-13	DGD21814	13	16	2500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



J;| = Manufacturer's marking
DGD21814 = Product Type Marking Code
YY = Year (ex: 19 = 2019)
WW = Week (01 to 53)

DGD21814 Document number: DS38329 Rev. 4 - 3

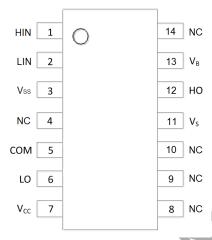
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Pin Diagrams

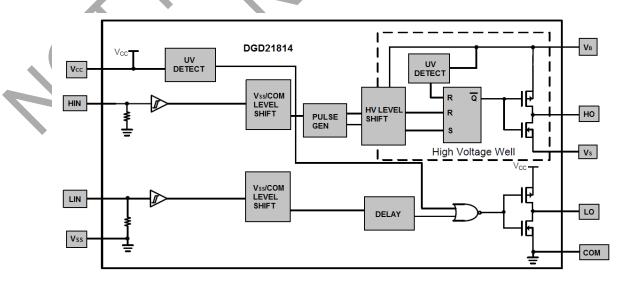


Top view SO-14

Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic input for high-side gate driver output, in phase with HO
2	LIN	Logic input for low-side gate driver output, in phase with LO
3	Vss	Logic ground
4, 8, 9, 10, 14	NC	No connection (No Internal Connection)
5	COM	Low-side and logic return
6	LO	Low-side gate drive output
7	Vcc	Low-side and logic fixed supply
11	Vs	High-side floating supply return
12	НО	High-side gate drive output
13	V _B	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	V _B	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Logic Supply Offset Voltage	V _{SS}	V _{CC} -24 to V _{CC} +0.3	V
Low-side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{OJA}	120	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	TL	+300	°C
Storage Temperature Range	T_{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V_{B}	V _S + 10	V _S + 20	V
High Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High Side Floating Output Voltage	Vho	Vs	V _B	V
Low Side Fixed Supply Voltage	Vcc	10	20	V
Low Side Output Voltage	V _{LO}	0	Vcc	V
Logic Input Voltage (HIN and LIN)	V _{IN}	0	Vcc	V
Logic Ground	Vss	-5	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V.





DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, @ T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage (Note 8)	V_{IH}	2.5	_	1	V	V _{CC} = 10V to 20V
Logic "0" Input Voltage (Note 8)	V_{IL}	_		0.8	V	V _{CC} = 10V to 20V
High Level Output Voltage, V _{BIAS} - V _O	V_{OH}	_		1.4	٧	$I_O = 0mA$
Low Level Output Voltage, Vo	V_{OL}	_	_	0.2	V	I _O = 20mA
Offset Supply Leakage Current	I_{LK}	_		50	μΑ	$V_B = V_S = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	20	60	150	μΑ	V _{IN} = 0V or 5V
Quiescent V _{CC} Supply Current	Iccq	50	120	240	μΑ	V _{IN} = 0V or 5V
Logic "1" Input Bias Current	I _{IN+}	_	25	60	μA	V _{IN} = 5V
Logic "0" Input Bias Current	I _{IN-}	_		5.0	μA	V _{IN} = 0V
V _{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	8.0	8.9	9.8	٧	
V _{BS} Supply Undervoltage Negative Going Threshold	V_{BSUV-}	7.4	8.2	9.0	>	_
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	8.0	8.9	9.8	V	_
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV} -	7.4	8.2	9.0	V	
Output High Short Circuit Pulsed Current	I _{O+}	1.4	1.9	_	Α	V _O = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I _{O-}	1.8	2.3		A	$V_0 = 15V$, PW $\leq 10 \mu s$

Note:

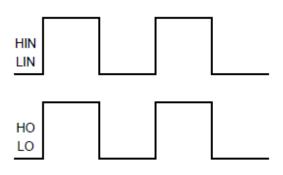
- 7. The V_{IN} and I_{IN} parameters are applicable to the two logic input pins: HIN and LIN. The V_{O} and I_{O} parameters are applicable to the respective output pins: HO and LO.
- 8. For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 2.5V with a minimum pulse width of

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, C_L = 1,000pF, @ T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	t _{ON}	_	180	270	ns	$V_S = 0V$
Turn-off Propagation Delay	toff	+	220	330	ns	V _S = 0V or 600V
Delay Matching, HO & LO Turn-on/off	t _{DM}			35	ns	_
Turn-on Rise Time	t _r	1-1	40	60	ns	V _S = 0V
Turn-off Fall Time	tf	1-7	20	35	ns	$V_S = 0V$



Timing Waveforms



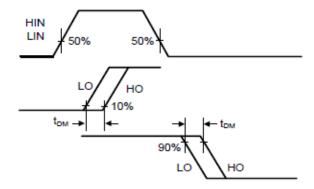


Figure 1. Input / Output Timing Diagram

Figure 2. Delay Matching Waveform Definitions

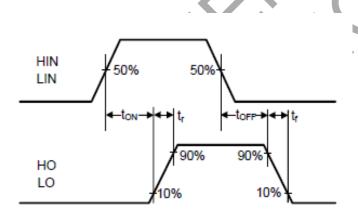


Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (Vcc=15V, @TA = +25°C, unless otherwise specified.)

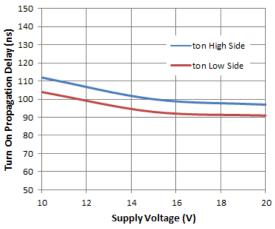


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

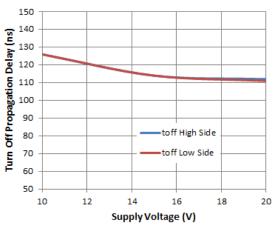


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

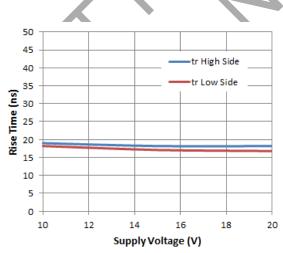


Figure 8. Rise Time vs. Supply Voltage

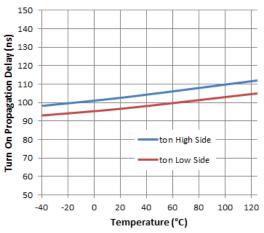


Figure 5. Turn-on Propagation Delay vs. Temperature

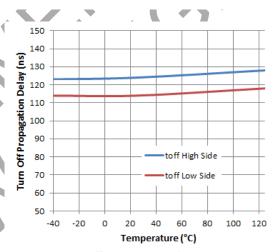


Figure 7. Turn-off Propagation Delay vs. Temperature

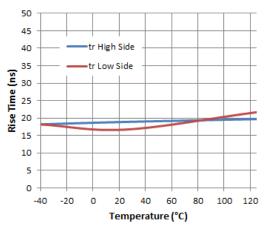


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Cont.)

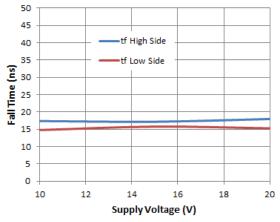


Figure 10. Fall Time vs. Supply Voltage

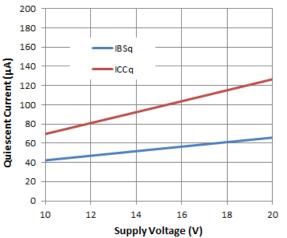


Figure 12. Quiescent Current vs. Supply Voltage

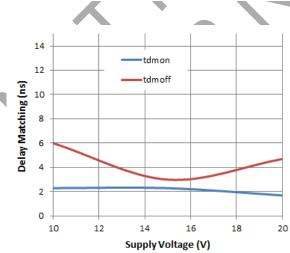


Figure 14. Delay Matching vs. Supply Voltage

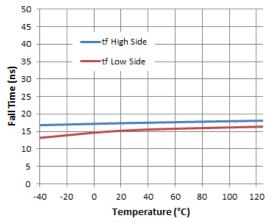


Figure 11. Fall Time vs. Temperature

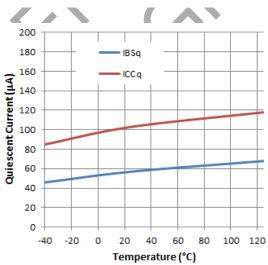


Figure 13. Quiescent Current vs. Temperature

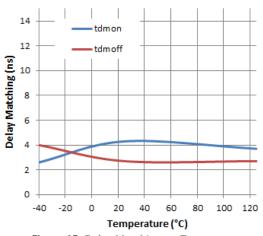


Figure 15. Delay Matching vs. Temperature



Typical Performance Characteristics (Cont.)

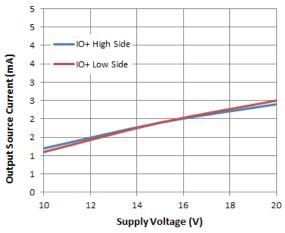


Figure 16. Output Source Current vs. Supply Voltage

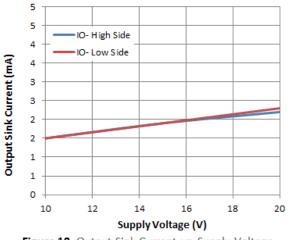


Figure 18. Output Sink Current vs. Supply Voltage

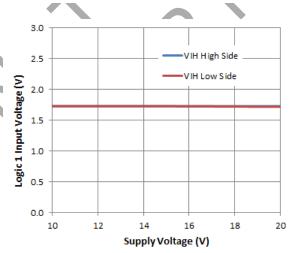


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

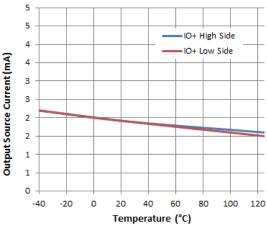


Figure 17. Output Source Current vs. Temperature

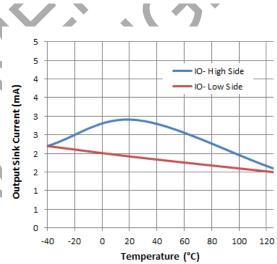


Figure 19. Output Sink Current vs. Temperature

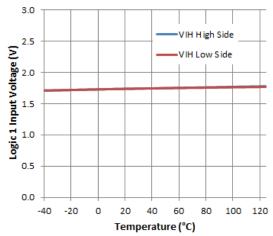


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.)

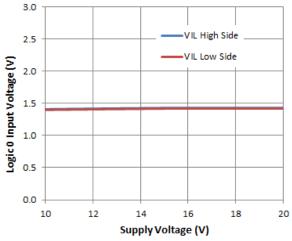


Figure 22. Logic O Input Voltage vs. Supply Voltage

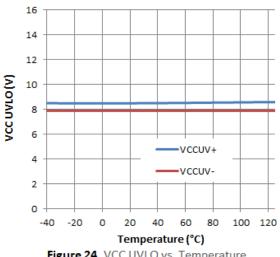


Figure 24. VCC UVLO vs. Temperature

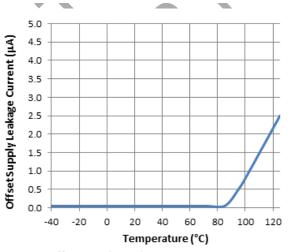


Figure 26. Offset Supply Leakage Current vs. Temperature

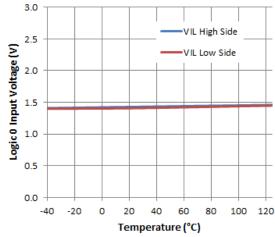


Figure 23. Logic 0 Input Voltage vs. Temperature

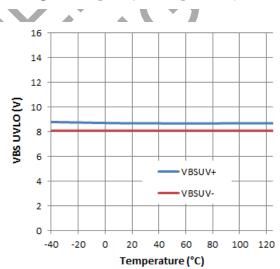


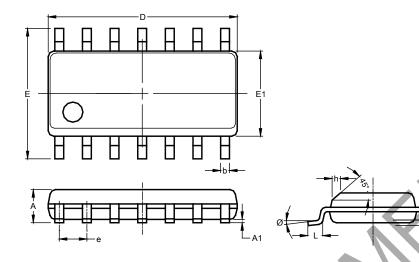
Figure 25. VBS UVLO vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14 (Type TH)

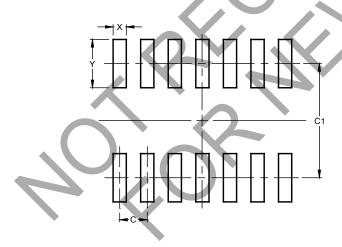


SO-14 (Type TH)					
Dim	Min	Max	Тур		
Α	1.55	1.73			
A1	0.10	0.25			
b	0.35	0.51			
С	0.190	0.248			
D	8.56	8.74	8.61		
Е	5.84	6.20	6.00		
E1	3.81	3.99	3.94		
е			1.27		
h	į	-	0.33		
_	0.41	0.89			
Ø	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
Х	0.60
V	2.20



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